

In Fig. 2B, a front side protection (or plug) layer 106 is deposited in the channel 129, and then the layer 112 is deposited. The substrate is then etched to form the slot. After the slot is formed, the layer 106 is removed from the channel 129 with a BOE (buffered oxide etch), as described in more detail below. In one particular embodiment, no additional etching of the slot is performed after the plug is removed. --

IN THE CLAIMS:

Please amend claims 1, 2, 11, and 24 as follows:

1. (Amended) A method of manufacturing a slotted substrate comprising:

- forming a masking layer over a front side of a substrate;
- patterning and etching the masking layer to form a hole therethrough;
- depositing a first layer over the masking layer and in the hole;
- patterning and etching the first layer to form a plug in the hole; and
- etching a back side of the substrate until a bottom surface of the plug is substantially exposed and a slot in the substrate is substantially formed.

2. (Amended) The method of claim 1 further comprising etching to remove the plug after etching the back side of the substrate to form the slot.

11. (Amended) A method of manufacturing a fluid ejection device comprising:

- forming a masking layer over a first surface of a substrate;
- patterning and etching the masking layer to form a hole therethrough;
- depositing a first layer over the masking layer and in the hole;
- patterning and etching the first layer to form a plug in the hole; and
- etching a second surface opposite the first surface of the substrate until a bottom surface of the plug is substantially exposed and a slot in the substrate is substantially formed.